

Title (en)  
ON THE FLY AUTOMATIC WAFER CENTERING METHOD AND APPARATUS

Title (de)  
VERFAHREN UND VORRICHTUNG FÜR SPONTANE AUTOMATISCHE WAFERZENTRIERUNG

Title (fr)  
PROCÉDÉ ET APPAREIL DE CENTRAGE AUTOMATIQUE DE TRANCHES À LA VOLÉE

Publication  
**EP 3341831 A1 20180704 (EN)**

Application  
**EP 16825130 A 20160713**

Priority  
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• US 2016042142 W 20160713

Abstract (en)  
[origin: TW201707900A] A substrate processing apparatus comprising a substrate transport apparatus having a self-centering end effector with a wafer holding station having a predetermined center, the end effector being configured to hold a wafer at the wafer holding station and transport the wafer within the substrate processing apparatus, at least one center deterministic feature integral to the substrate transport apparatus and disposed so that a static detection sensor of the substrate processing apparatus detects at least one edge of the at least one center deterministic feature on the fly with the substrate transport apparatus radial motion, and a controller communicably coupled to the substrate transport apparatus, the controller being configured so that detection of the at least one edge effects a determination of a proportion factor identifying a variance of an arm of the substrate transport apparatus on the fly with the substrate transport apparatus radial motion, wherein the controller includes a kinematic effects resolver configured to determine, from the detection of the at least one edge, a relation between a proportion factor variance and the detection of the at least one edge by the static detection sensor of the substrate transport apparatus on the fly with the substrate transport apparatus radial motion and further resolve effects of the determined proportion factor variance on the proportion factor determining the variance of the arm.

IPC 8 full level  
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Cited by  
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CN 201680053111 A 20160713; CN 202210281765 A 20160713; EP 16825130 A 20160713; TW 105122083 A 20160713; TW 110148501 A 20160713